

## TECHNICAL CHARACTERISTICS

### 1. General Characteristics

Dimension: 61.00L x 37.00W x 6.70H mm  
 Weight: Approx. 6.5 g  
 Contact principle: Friction technology  
 Operating position: Shaft up / Down / Horizontal  
 Mounting System: Thru-Hole with snap-in lock  
 (PCB Thickness= 1.2mm or 1.6mm)  
 Durability: 5,000 cycles min.

### 2. Mechanical Characteristics

Insulation material: Thermoplastic, UL 94V-0  
 RoHS Directive 2011/65/EU Compliant

### 3. Electrical Characteristics

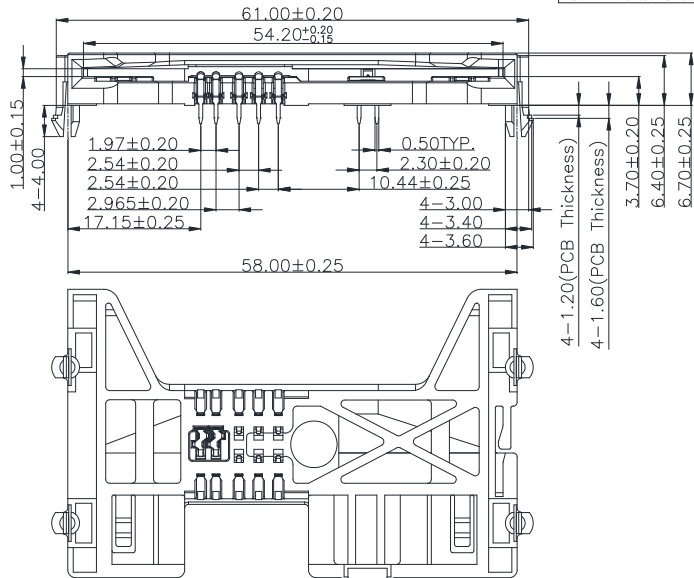
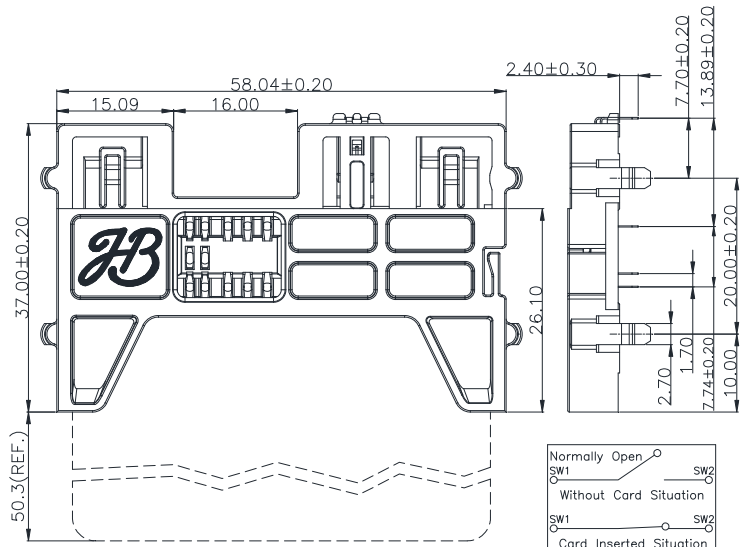
Number of contacts: 12 pins  
 Contact resistance: 100 mΩ max.  
 Insulation resistance: >1000 MΩ / 500 VDC  
 Switch type: Blade  
 Operation: Normally Open

### 4. Solderability

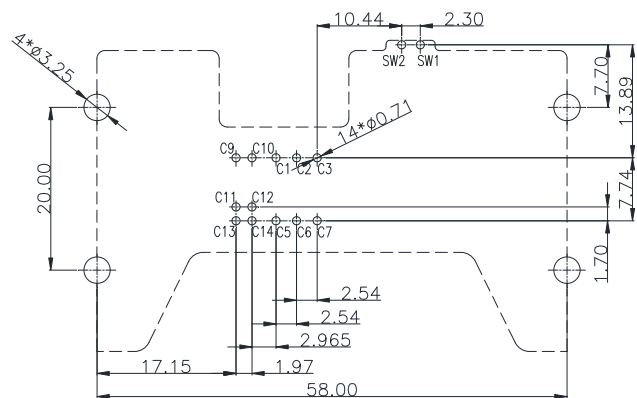
Wave: 260°C, 5 sec. Max.  
 IR reflow: Not applicable  
 Manual soldering: 360°C, 3 sec. Max.

### 5. Environmental Characteristics

Operating temperature: - 40°C ~ + 85°C  
 Operating humidity: 10 % ~ 95 % RH  
 Storage temperature: - 40°C ~ + 85°C  
 Storage humidity: 10 % ~ 95 % RH



Unit: mm; Tolerances: ±0.15 mm  
 Mechanical outline dimension



Unit: mm; Tolerances: ±0.05 mm  
 Reference dimension for PCB layout

HB TSIO Card Acceptor

Model No.: TSO-G02

Revision: 1.0

Date: JAN. 23, 2019